

APPLICATION DATA SHEET

Electronic Version v14

Stylesheet Version v14.0

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Title of
Invention

Electromagnetic wave shielding window, manufacturing apparatus
having the same, transport system having the same, building
construction having the same, and electromagnetic wave shielding
method

Application Type: regular, utility

Attorney Docket Number: 36607

Correspondence address:

Customer Number:

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Continuing Data:

This is a Continuation of IB application number PCT/JP01/08459, filed 2001-09-27.

Priority Data:

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as our attorney(s) or agent(s) to prosecute the application identified above, and to transact all business in the United States Patent and Trademark Office connected therewith.

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